TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIV)

TPC8114

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

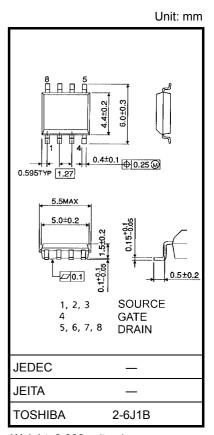
- Small footprint due to small and thin package
- Low drain-source ON resistance: $RDS(ON) = 3.1 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 47 \text{ S (typ.)}$
- Low leakage current: $IDSS = -10 \mu A (max) (VDS = -30 V)$
- Enhancement-mode: V_{th} = -0.8 to -2.0 V (V_{DS} = -10 V, I_{D} = -1 mA)

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-30	V	
Drain-gate voltage (Ro	$_{\rm SS} = 20 \text{ k}\Omega$)	V_{DGR}	-30	V	
Gate-source voltage		V_{GSS}	±20	٧	
Drain current	DC (Note 1)	ID	-18	Α	
	Pulse (Note 1)	I_{DP}	-72		
Drain power dissipatio	n (t = 10 s) (Note 2a)	P_{D}	1.9	W	
Drain power dissipatio	n (t = 10 s) (Note 2b)	P _D	1.0	W	
Single pulse avalanche	e energy (Note 3)	E _{AS}	211	mJ	
Avalanche current		I _{AR}	-18	Α	
Repetitive avalanche (N	energy lote 2a) (Note 4)	E _{AR}	0.19	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature r	ange	T _{stg}	-55 to 150	°C	

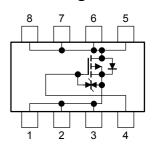
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

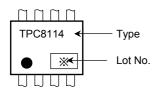
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

Marking (Note 5)

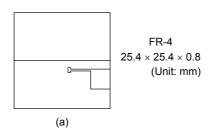


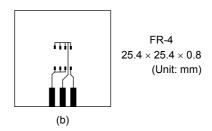
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

(a) Device mounted on a glass-epoxy board (b) (b) Device mounted on a glass-epoxy board (b)

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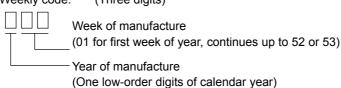


Note 3: $V_{DD} = -24 \text{ V}$, $T_{Ch} = 25^{\circ}\text{C}$ (initial), $L = 500 \,\mu$ H, $R_G = 25 \,\Omega$, $I_{AR} = -18 \,\text{A}$

Note 4: Repetitive rating; pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

 Weekly code: (Three digits)



Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage curre	ent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_			μА	
Drain cut-OFF cur	rent	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	<u> </u>		-10	μА	
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V	
Dialii-Source brea	kdown voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	±10 10	v			
Gate threshold voltage		V _{th}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V	
Drain-source ON resistance Forward transfer admittance		D (2)	$V_{GS} = -4 \text{ V}, I_{D} = -9 \text{ A}$	_	5.2	6.8	- mΩ	
		KDS (ON)	V _{GS} = -10 V, I _D = -9 A	_	3.1	4.5		
Forward transfer admittance		Y _{fs}	$V_{DS} = -10 \text{ V}, I_{D} = -9 \text{ A}$	23.5	47	_	S	
Input capacitance		C _{iss}		_	7480	_		
Reverse transfer capacitance		C _{rss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	1320	_	pF	
Output capacitance		Coss		_	1460	_		
	Rise time	t _r	Vos 0 V 7	_	25	_		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	-10 V OUT	_	36	_				
	Fall time	t _f	4.7.5 W.W. 1 = 1	_	235	_	ns	
	Turn-OFF time	t _{off}	$V_{DD} \simeq -15 \text{ V}$ Duty \leq 1%, $t_W = 10 \mu\text{s}$	_	625	_		
		Qg		_	180	_	nC	
Gate-source charge 1		Q _{gs1}		_	10	_		
Gate-drain ("miller") charge		Q _{gd}]	_	60	_		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	-72	Α
Forward voltage (diode)		V _{DSF}	$I_{DR} = -18 \text{ A}, V_{GS} = 0 \text{ V}$			1.2	V	

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